

# ProbePads 05



## APPLICATIONS

- Device characterization
- Microwave integrated circuits
- On-wafer microwave measurements
- De-embedding

## FEATURES

- Wire bondable Au contacts
- Eutectic, epoxy, or solder die attach
- Compact and low profile
- 99.6% Alumina
- Thin-film process

## SPECIFICATIONS

TABLE 1: TYPICAL SPECIFICATIONS\*

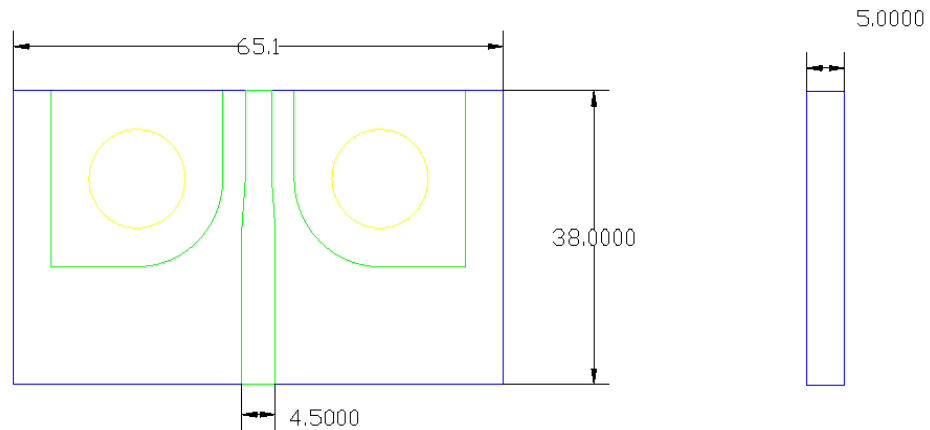
FREQ (GHz)	PART NUMBER	INSERTION LOSS (dB)	RETURN LOSS (dB)	SUBSTRATE	PROBE TIP SPACING	SIZE (MILS)
DC-26.5	PPS-005-01	0.25	20	99.6% ALUMINA	150-250 um	65 X 38 X 5

\* Specifications subject to change without notice.

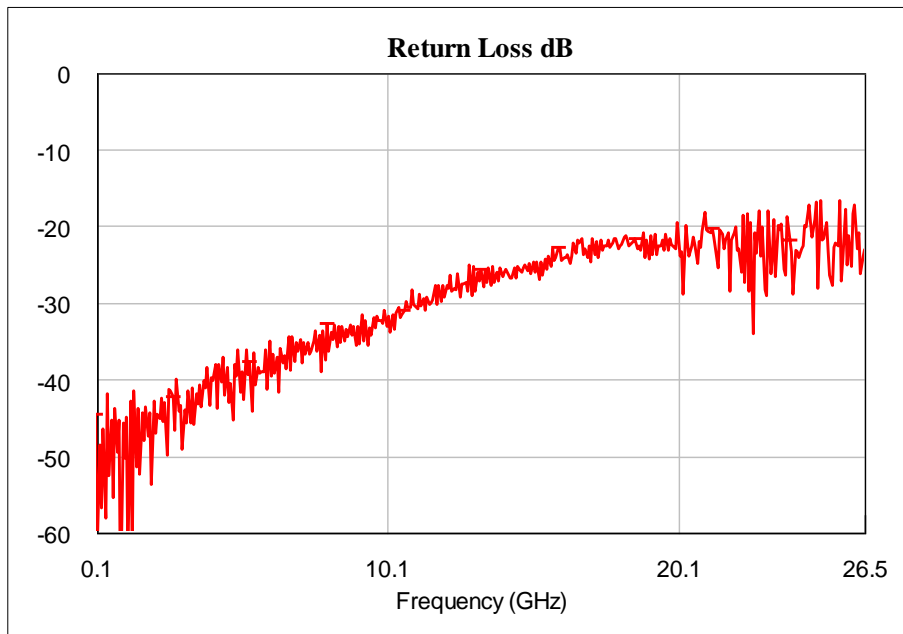
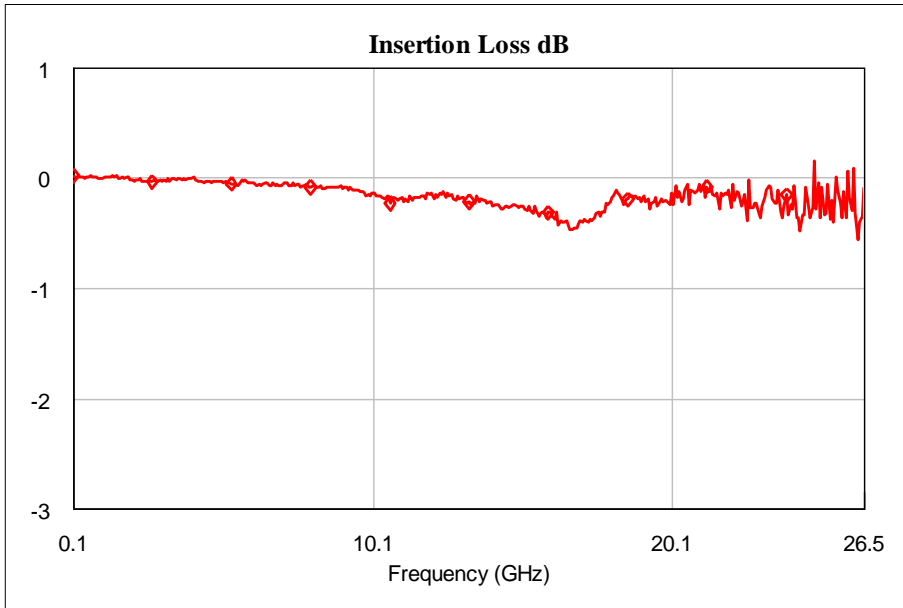
## MECHANICAL

\* Dimensions are mils

- 99.6%Alumina
- Metallization: Gold



## TYPICAL PERFORMANCE



Data taken with two back-to-back ProbePads 05 mounted on a gold-plated copper tungsten carrier with Epo-Tek H20E epoxy. Measured on a probe station with GGB EPC40-GSG-150 probes and CS5 calibration substrate.

# ProbePads 05

CPWG to microstrip transition

REV 1.0.0

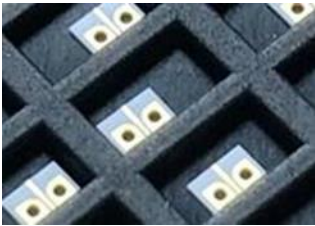
## ORDERING INFO

PPS - 005 - 01  
①                      ②                      ③

①                      ②                      ③  
**PRODUCT CODE**

CPWG TO MICROSTRIP  
TRANSITION

**Packaging:** Waffle Pack



The PPS-005-01 is a lead free, RoHS compliant product.